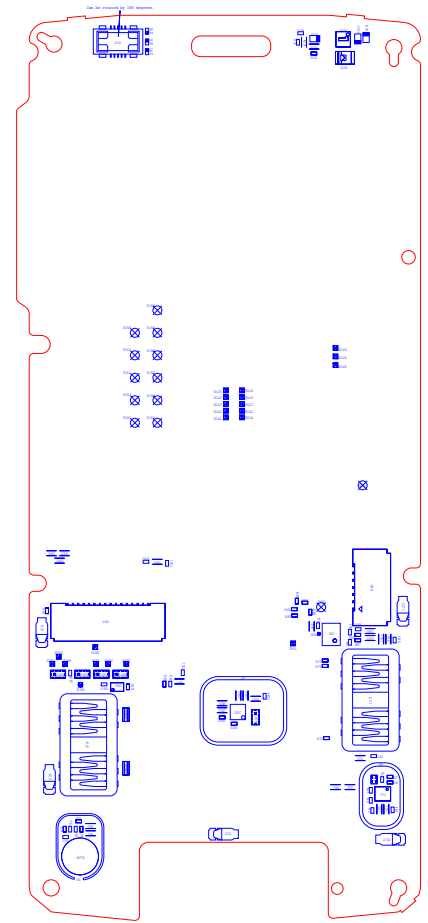



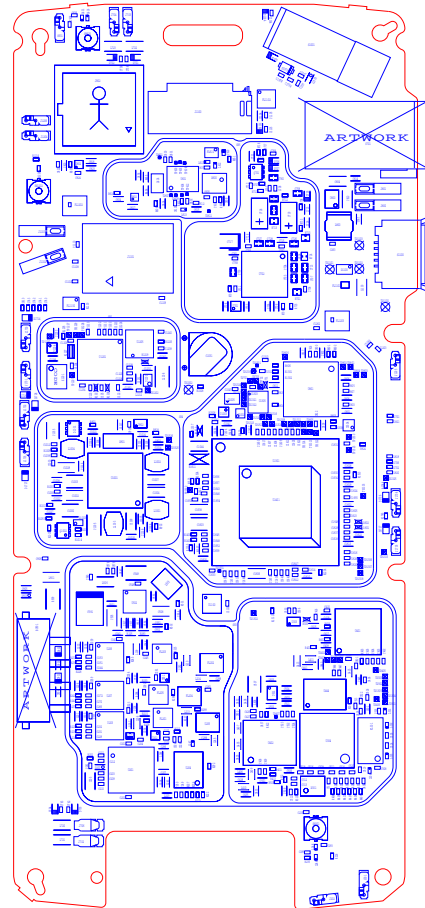
REVISIONS				
REV	ECN	DESCRIPTION	DFTS	DATE
1	18506	PRODUCTION RELEASE	FB	10.04.29
2	18215	ECR 3659 BOM CORRECTION	AR	10.06.16



THE SOLDER AND ASSEMBLY PROCESS SHALL COMPLY WITH DIRECTIVE 2002/95/EC (ROHS) AND IM ENVIRONMENTAL SPECIFICATION

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TITLE                      PRINTED WIRING BOARD Printed Wiring Board	
RIM CONFIDENTIAL                      REV: 2	
APPROVALS	DATE
DRAWN BY: A. Roemer	10.06.11
A SIZE	DWG. NO. POP-24462-013 SCALE 1:1
SHEET 1 of 2	



Explanations:

- ☐ = Artwork components -> DNP
- X = DNP components
- ⊗ ⊗ ⊗ = TPxxx = Testpoints

NOTES:

1. MAXIMUM BREAKAWAY VESTIGE FROM MAIN EDGE SHALL BE +/- 0.3mm.
2. ACCEPTABILITY OF ASSEMBLY TO MEET IPC 610 (LATEST ISSUE), CLASS 2.
3. THE SOLDER AND ASSEMBLY PROCESS SHALL COMPLY WITH DIRECTIVE 2002/95/EC (ROHS)BE +/- 0.3mm. AND RIM ENVIRONMENTAL SPECIFICATIONS.

THE SOLDER AND ASSEMBLY PROCESS SHALL COMPLY WITH DIRECTIVE 2002/95/EC (ROHS) AND RIM ENVIRONMENTAL SPECIFICATION



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